

CBTech®

川寶科技股份有限公司

MAKE
EXPOSURE
EASY.

TiTAN 8000 SERIES



TiTAN 8000

TiTAN 8000PSR

TiTAN 9000DFR

TiTAN 8000DFR



川寶科技提供PCB各製程 內層/外層/防焊 不同需求直接成像曝光機
CBT offers models with different functionalities: PCB inner layer,
outer layer, solder mask to corporator every needs

3in1

少量多樣單機3合1機型

3-in-1 model all around with
just one machine.



外層/防焊高速雙面自動機

Outer/Solder Mask high-speed
double-sided automation.



內/外層單機雙面自動機

SDDS automation for
Inner/outer layer.



最符合生產線的自動機設計理念

The most suitable model for the
fully automatic production line.

TiTAN 8000 內層/外層/防焊 3合1 直接成像曝光機

Inner Layer/Outer Layer/Solder Mask 3-in-1 Direct imaging Machine



內層免鑽孔對位專利

Hole free registration patent



半自動機 Standalone

內層
Inner
V

外層
Outer
V

防焊
Solder Mask
V

特色 / Features:

- 採DMD投影系統及高功率多波長LED，內外層乾膜解析40μm，防焊SRO 4mil，業界唯一3合1機型
Adapt DMD imaging technology and high power multi wavelength LED，inner and outer layer registration of 40μm，Solder Mask SRO 4mil，The one and only 3-in-1 model in the market.
- 彈性可選擇 2 - 14支投影頭，最大成像面積26" x32"
With the Flexibility to choice 2-14 print heads，and the attainability of 26" x32" print size

規格 / Specification:

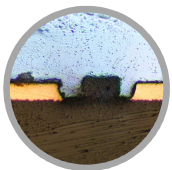
應用	Application	乾膜內外層 Dry Film/ Inner ,Outer 防焊 Solder Mask
板尺寸	Board size	546mmX812mm(23"X32"標準成像面積) 660mmX812mm(26"X32"彈性成像面積)
板厚	Board Thickness	0.01~8mm
解析能力	Resolutions	40μm/40μm
內層對位精度	Registration inner	≤12μm
外層對位精度	Registration outer	36≤10μm
乾膜種類	DFR Type	DI 專用乾膜/一般乾膜 Low intensity dry film/ regular dry film
濕膜種類	Ink Type	DI 專用濕膜/一般濕膜 Low intensity Ink/ regular Ink
單機產速 by 20"	Standalone throughput By 20"	20mj/cm² 6CH 2100pnls/day(內層) 50mj/cm² 6CH 1700pnls/day 250mj/cm² 6CH 1000pnls/day(防焊)

TiTAN 8000PSR 防焊用直接成像曝光機

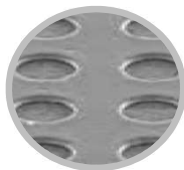
Solder Mask Direct imaging Machine



半自動機 Standalone



3mil Dam



墨厚 : 25µm
SRO : 4mil

特色 / Features:

- 成像頭6頭/14頭供選擇
Option of Six and fourteen print head
- CBT 防焊DI搭載高功率三波長UV LED. SRO 4mil
CBT Solder Mask DI machine with high efficiency triple wavelength UV LED、SRO 4mil.
- 軟板專用自動化連線
Specialized automated connection for flexible PCB
- 夾板設計
Board clumper design

規格 / Specifications:

應用	Application	防焊 Solder mask
板尺寸	Board size	546mmX812mm(23"X32"標準成像面積) 660mmX812mm(26"X32"彈性成像面積)
板厚	Board Thickness	0.01~8mm
解析能力	Resolutions	SRO 4mil/ Dam 2.5mil
防焊對位精度	Registration Solder Mask	3 σ ≤10µm
油墨種類	Ink Type	DI 專用濕膜/一般濕膜 Low intensity Ink/ Regular Ink
單機產速 by 20"	standalone throughput	250mj/cm ² 6CH 1000 panels/Day 250mj/cm ² 12CH 1700 panels/day

TiTAN 8000DFR 40μm 線路用直接成像曝光機

40μm Direct imaging Machine



特色 / Features:

- 獨特專利-內層免鑽孔兩面對位精度達 $\leq 12\mu\text{m}$. 解析能力 $40\mu\text{m}$.
Exclusive patent –inner Layer drilling-free registration accuracy of $\leq 12\mu\text{m}$ resolutions capability of $40\mu\text{m}$.
- 可搭配單機雙面自動化及雙機連線自動化
With the ability to comprehend with SDDS automatic and the Dual DI automatic machine
- 彈性可選擇 2 - 14支投影頭,最大成像面積 26" x 32"
With the flexibility to choosing 2 - 14 print heads and the attainability of 26" x 32" print size

規格/ Specifications:

應用	Application	乾膜內外層 Dry Film/ Inner ,Outer
板尺寸	Board size	546mmX812mm(23"X32"標準成像面積) 660mmX812mm(26"X32"彈性成像面積)
解析能力	Resolutions	40μm/40μm
內層對位精度	Registration inner	$\leq 12\mu\text{m}$
外層對位精度	Registration outer	$3\delta \leq 10\mu\text{m}$
乾膜種類	DFR Type	405nm dry film
單機連線產速 by 20"	SDDS Automatic throughput	20mj/cm ² 6CH 2100 panels /day (內層) 50mj/cm ² 6CH 1700 panels /day
雙機連線產速 by 20"	Dual Automatic throughput	20mj/cm ² 6CH 4200 panels /day (外層) 50mj/cm ² 6CH 3400 panels /day

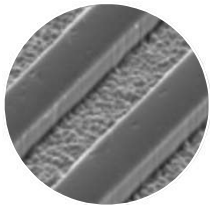


半自動機
Standalone

單機自動機
SDDS Automatic

雙機連線自動機
Dual DI Automatic

單機自動機 SDDS automatic



L/S 40μm



內層免鑽孔對位專利
Hole free registration patent

TiTAN 9000DFR 25μm 線路用直接成像曝光機

25μm Direct imaging Machine



雙機自動機 Dual automatic



L/S 25μm



內層免鑽孔對位專利
Hole free registration patent

特色 / Features:

- 獨特專利-內層免鑽孔兩面對位精度達 $\leq 12\mu\text{m}$. 解析能力 $25\mu\text{m}$.
Exclusive patent -inner Layer drilling-free registration accuracy of $\leq 12\mu\text{m}$ resolutions capability of $25\mu\text{m}$.
- 可搭配單機雙面自動化及雙機連線自動化
With the ability to comprehend with SDDS automatic and the Dual DI automatic machine
- 彈性可選擇 2 - 14支投影頭,最大成像面積 26" x 32"
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規格/ Specifications:

應用	Application	乾膜內外層 Dry Film/ Inner ,Outer
板尺寸	Board size	546mmX812mm(23"X32"標準成像面積) 660mmX812mm(26"X32"彈性成像面積)
解析能力	Resolutions	25μm/25μm
內層對位精度	Registration inner	$\leq 12\mu\text{m}$
外層對位精度	Registration outer	$3\delta \leq 10\mu\text{m}$
乾膜種類	DFR Type	405nm dry film
單機連線產速 by 20"	SDDS Automatic throughput	20mj/cm ² 6CH 1900 panels /day (內層) 50mj/cm ² 6CH 157000 panels /day
雙機連線產速 by 20"	Dual Automatic throughput	20mj/cm ² 6CH 3600 panels /day (外層) 50mj/cm ² 6CH 3000 panels /day



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Thanks for your attention
PCB exposure solution provider

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